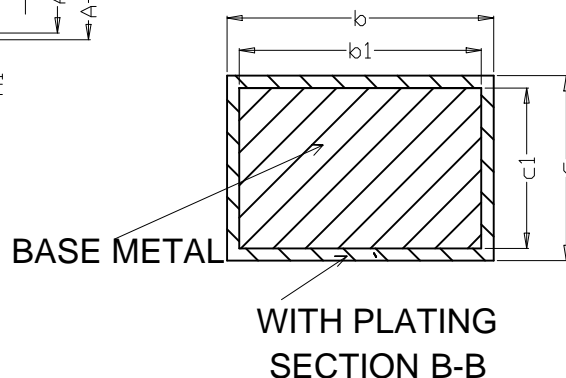
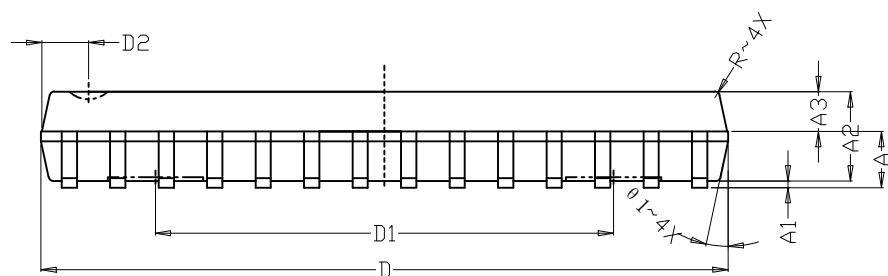
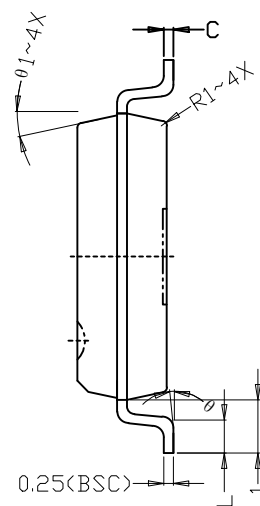
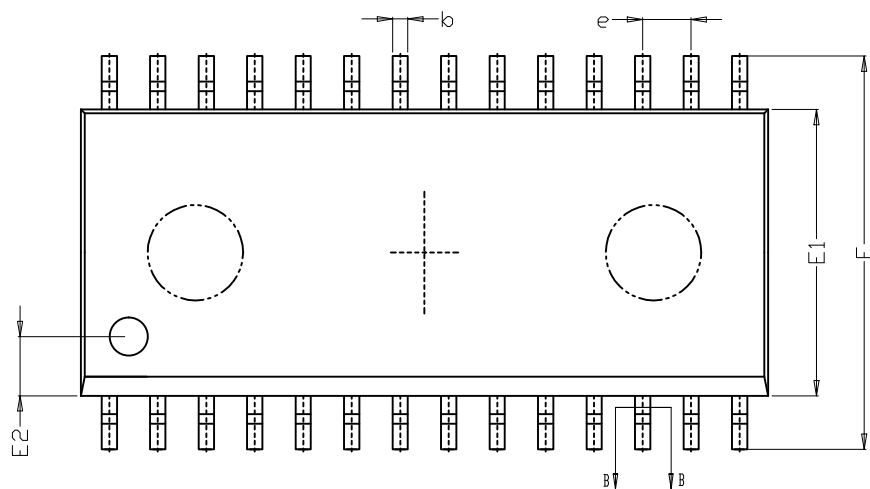




MARK	MARK
△	
△	



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	2.615
A1	0.10	--	0.30
A2	2.29	2.34	2.39
A3	0.99	1.043	1.07
b	0.39	--	0.47
b1	0.38	0.41	0.44
c	0.25	--	0.29
c1	0.24	0.25	0.26
D	17.90	18.00	18.10
D1	11.90	12.00	12.10
D2	1.225(BSC)		
E	10.10	10.30	10.50
E1	7.40	7.50	7.60
E2	1.55(BSC)		
e	1.27(BSC)		
L	0.854	0.864	0.874
L1	1.403(REF)		
θ	0°	~	8°
θ 1	6°	~	15°
R/R1	R1.27(BSC)		

技术说明:

- 1) LEADFRAME MATERIAL: COPPER;
引线框架材料: 铜;
- 2) LEADFRAME THICKNESS: 0.254mm;
引线框架厚度: 0.254mm;
- 3) BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;
塑封体长度及宽度尺寸不包括塑封溢胶;
- 4) REFERENCE: JEDEC MS-013, MS-012.
参考标准: JEDEC MS-013, MS-012.

NO.	NAME	Q'TY	MATERIAL	DIMENSION		FINISH	HARDING	REMARK
			SCALE	UNIT	mm	TITLE		
			DATE	2021-04-30		SOP28L产品成型图		
TOLERANCE			DESIGNER	CHECKER	APPROVER	DWG.NO.		
			陈露			MT-PD-047		
			2021-04-30			VERSION		
						A		